X11DSF-E (For SuperServer Only)



24 DIMMs NVMe 3 UPI

Key Features

- 1. 2nd Gen Intel® Xeon® Scalable Processors and Intel® Xeon® Scalable Processors

 Dual Socket LGA-3647 (Socket P) supported, CPU TDP support Up to 205W TDP, 3 UPI up to 10.4 GT/s
- 2. Intel® C627
- 3. Up to 6TB 3DS ECC RDIMM, DDR4-2933MHz; Up to 6TB 3DS ECC LRDIMM, DDR4-2933MHz, in 24 DIMM slots; Up to 6TB Intel® Optane™ DC Persistent Memory in memory mode (Cascade Lake only)
- 4. 1 PCI-E 3.0 x32 Left Riser Slot, 2 PCI-E 3.0 x4 (Low Profile), 4 PCI-E 3.0 x16
- 4 FOI-E 3.0 X 10
- 5. Dual LAN with 10GBase-T with Intel® X550
- 6. Intel® C627 controller for 8 SATA3 (6 Gbps) ports; RAID 0,1,5,10
- 7. 1 VGA D-Sub Connector port

Specifications

Expansion Slots

PCI-E	■ 1 PCI-E 3.0 x32 Left Riser Slot,

■ 2 PCI-E 3.0 x4 (Low Profile),

■ 4 PCI-E 3.0 x16

System BIOS

BIOS Type AMI UEFI

Management

Software ■ SuperDoctor® 5, NMI, <u>SUM</u>, KVM with dedicated LAN, SPM, Intel® Node Manager, SSM, IPMI2.0, Watchdog, IPMI (Intelligent Platform Management Interface) v2.0 with KVM support ■ IPMI (Intelligent Platform System Management

Software

Management Interface) v1.5 / 2.0 with KVM support

PC Health Monitoring

Voltage	■ VBAT, Monitors CPU voltages, Chipset Voltage, +5V standby, +5V, +3.3V, +12V, +1.8V, +1.5V, Memory Voltages
LED	UID/Remote UIDCPU / System Overheat LED
FAN	 8x 4-pin fan headers (up to 8 fans) Fan speed control Pulse Width Modulated (PWM) fan connectors Overheat LED indication 8x fans with tachometer monitoring
Other Features	■ WOL, UID, System level control, RoHS, Node Manager Support, CPU thermal trip support for processor protection, Control of power-on for recovery from AC power loss, Chassis intrusion header, Chassis intrusion detection, RoHS, Halogen Free, Intel® QuickAssist Technology, Innovation Engine

Operating Environment

Operating Temperature Range	■ 10°C - 35°C (50°F - 95°F)
Non-Operating Temperature Range	■ -40°C - 70°C (-40°F - 158°F)
Operating Relative Humidity Range	8% - 90% (non-condensing)

Product SKUs

MBD-X11DSF-E X11DSF-E

Non Operating 5% - 95% (non-condensing)
Relative
Humidity
Range

Physical Stats

Form Factor	Proprietary	
Dimension	■ 16.337" x 17" (41.5cm x 43.18cm)	

Processor

Processor	
CPU	 2nd Gen Intel® Xeon® Scalable Processors and Intel® Xeon® Scalable Processors Dual Socket LGA-3647 (Socket P) supported, CPU TDP supports Up to 205W TDP, 3 UPI up to 10.4 GT/s
Note	 *2933 MHz in two DIMMs per channel can be achieved by using memory purchased from Supermicro

System Memory

Memory Capacity	 24 DIMM slots Up to 6TB 3DS ECC LRDIMM, DDR4-2933MHz; Up to 6TB 3DS ECC RDIMM, DDR4-2933MHz Up to 6TB Intel® Optane™ DC Persistent Memory in memory mode (Cascade Lake only)
Memory Type	2666/2400/2133MHz ECC DDR4 LRDIMM (3DS), RDIMM (3DS)
DIMM Sizes	■ LRDIMM: 64GB, 128GB ■ RDIMM: 32GB, 64GB, 128GB
Memory Voltage	" 1.2V
Error Detection	Corrects single-bit errorsDetects double-bit errors (using ECC memory)

On-Board Devices

Chipset	■ Intel® C627
SATA	Intel® C627 controller for 8 SATA3 (6 Gbps) ports; RAID 0,1,5,10
IPMI	■ ASPEED AST2500
Network Controllers	Dual LAN with 10GBase-T with Intel® X550

Input / Output

USB	3 USB 3.2 Gen1 port(s) (2 via header; 1 type A)2 USB 3.0 port(s) (2 rear)
Video Output	■ 1 VGA D-Sub Connector port(s)
Serial Port	■ 1 COM Port(s) (1 header)
DOM	 2 Super<u>DOM</u> (Disk on Module) port with build power
TPM	■ 1 TPM Header

Parts List

Parts List (Bulk Package)			
Name	Part Number	Qty	Description
Motherboard	MBD-X11DSF-E	1	X11DSF-E Motherboard

Optional Parts List			
Name	Part Number	Qty	Description
TPM security module (optional, not included)	<u>AOM-TPM-9670V</u>		SPI capable TPM 2.0 with Infineon 9670 controller with vertical form factor

Server (Optimized for X11DSF-E)

	Server Name
SSG-1029P-NES32R	

- ◀